IN THE SPECIFICATION

3 2
Paragraph spanning pages 7-8:

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IDC-A1,AMD

Referring to FIG. 7, each of the filtering channel structures 1 has a first through hole 10 and a first concave portion 11 connected to each other, the first concave portion 10 defining two first channel portions 12 opposite each other, and each of the first channel portions 12 having a plurality of channels 120 and openings 121. Referring to FIG. 8, each of the through channel structures 2 respectively connects to the filtering channel structures 1 by an anode joint so as to provide more than two filtering effects. The filtering channel structures and the through channel structures are made of a silicon wafer. Each of the through channel structures 2 defines a second through hole 20 and a second concave portion 21 connected to each other. The second through hole 20 is opposite the first concave portion [[21,]] 11, and the second concave portion 21 defines two second channel portions 22 opposite each other. Each of the second channel portions 22 has a plurality of channels 220 and openings 221. A base structure 3 is connected to a bottom of the through channel structures 2 and has a plurality of through hole 30 therein to strengthen the micro-filter.

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